

HD MEZZ™ ARRAY SOCKET HDAF SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HDAF

- Insulator Material:** Black Liquid Crystal Polymer
- Contact Material:** Copper Alloy
- Current Rating:** Testing Now!
- Operating Temp Range:** -55°C to +125°C
- Plating:** Au or Sn over 50µ" (1.27µm) Ni
- Contact Resistance:** Testing Now!
- Working Voltage:** Testing Now!
- Mated Cycles:** Testing Now!

Processing:

- Max Processing Temp:** 230°C for 60 seconds with Type -1 solder crimp, or 230°C for 60 seconds, or 260°C for 20 seconds 3x with Type -2 solder crimp
- Lead-Free Solderable:** Type -1: No
Type -2: Yes

Mates with:
HDAM



| MATED HEIGHTS* | | |
|-----------------|-----------------|------|
| HDAF LEAD STYLE | HDAM LEAD STYLE | |
| -08.0 | 20mm | 30mm |
| -18.0 | 25mm | 35mm |

*Processing conditions will affect mated height.

*HD Mezz™ is a trademark of Molex, Inc.

Open pin field for Single-Ended or Differential Pair configurations

1,2mm x 2mm grid

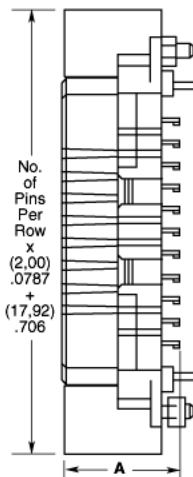
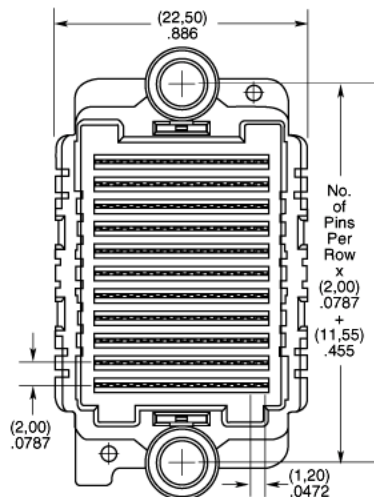
299, 195 and 143 pins

High density elevated board-to-board

Elevated stack heights of 20mm, 25mm, 30mm and 35mm

Choice of Tin-Lead or Lead-Free Solder Crimps

| HDAF | NO. OF PINS PER ROW | LEAD STYLE | PLATING OPTION | NO. OF ROWS | SOLDER TYPE | OTHER OPTION |
|------|---------------------|-------------------------------|--|-------------|--|-----------------------|
| | -11, -15, -23 | Specify LEAD STYLE from chart | -S = 30µ" (0.76µm) Gold on contact area, Matte Tin on tails and guide pins | -13 | -1 = 63% Sn/37% Pb Solder Crimp -2 = Lead-Free Tin Alloy 95.5% Sn/ 3.8% Ag/0.7% Cu Solder Crimp | -P = Pick & Place Pad |



| LEAD STYLE | A |
|------------|--------------|
| -08.0 | (10,51) .414 |
| -18.0 | (20,51) .807 |

Note: Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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